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(54) METHOD FOR PEELING SEED

(57) Abstract

PURPOSE: To selectively pulverize and remove only seed coats by mixing seeds with a mixed abrasive material of coarse abrasive grains and fine abrasive grains and stirring the resultant mixture.

CONSTITUTION: Seeds are mixed a mixed abrasive material of coarse abrasive grains and fine abrasive grains and stirred. The seeds which are objects are seeds of vegetables such as Japanese radish, Chinese cabbage or lettuce, beans such as mung bean,

soybean, ADZUKI bean or peanut and nuts such as walnut or chestnut. For example, alumina, silica, zirconia, corundum, glass and silica sand are cited as the material for the above-mentioned mixed abrasive material. Abrasive grains having about 50 μ m to 20mm grain diameter are used as the coarse abrasive grains and abrasive grains having about 20-1700 μ m grain diameter are used as the fine abrasive grains. The mixing ratio of the coarse abrasive grains to the fine abrasive grains is about (10:1)-(1:10) weight ratio. After the aforementioned treatment, peeled seeds are separated from the mixed abrasive material by a means, e.g. screening or winnowing.

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